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## 10561696 **Application Number** Filing Date 2007-03-09 INFORMATION DISCLOSURE First Named Inventor Yuji Yakura STATEMENT BY APPLICANT <del>-2053.</del> 2861 Art Unit (Not for submission under 37 CFR 1.99) **Examiner Name** S Hsieh Attorney Docket Number 09792909-6568

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|   |        |   | DISCLOSURE                | First Named Inventor        | Yuji Y  | Yakura                |               |  |  |  |
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